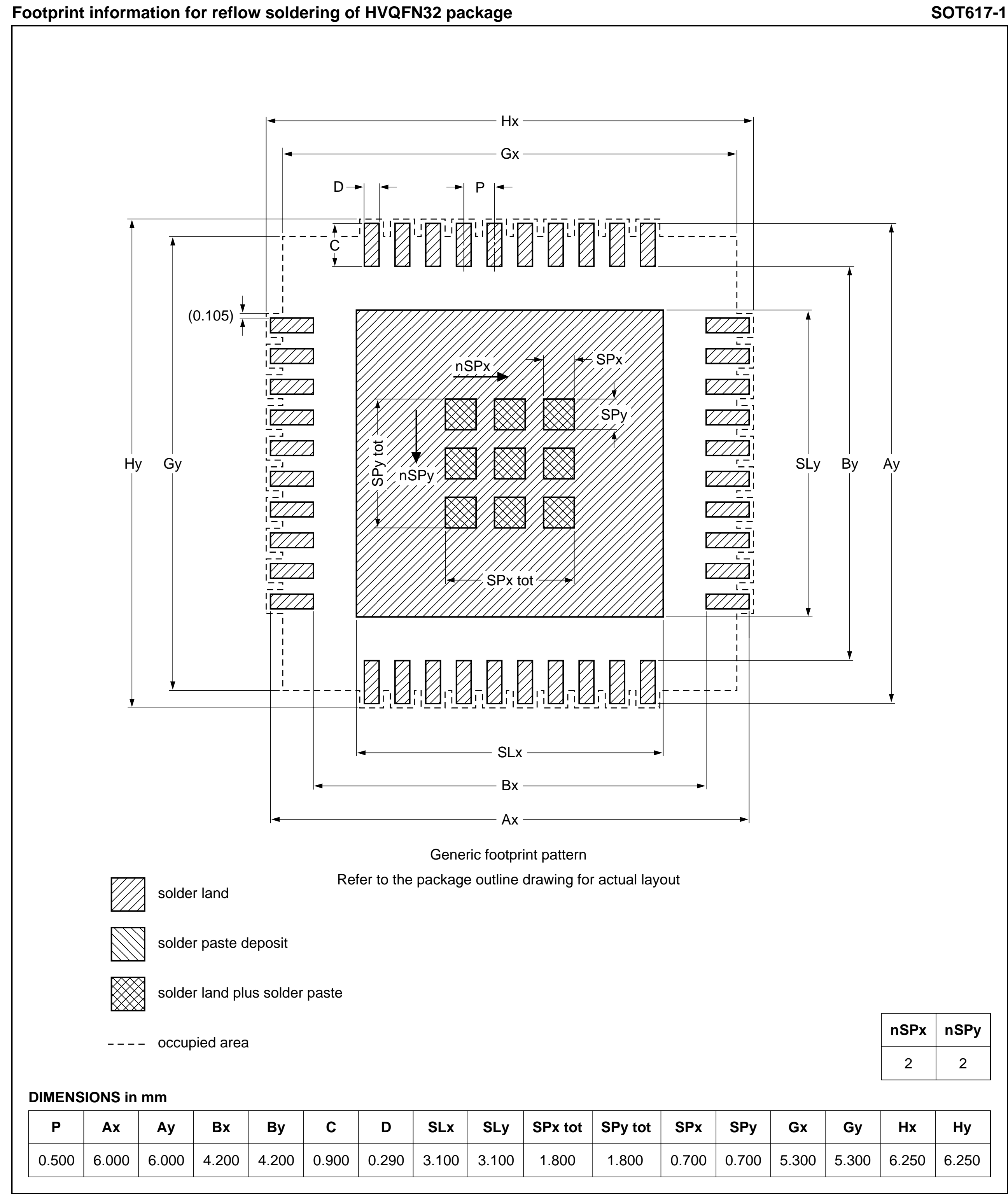
Footprint information for reflow soldering of HVQFN32 package — **SOT617-1**



Generic footprint pattern

Refer to the package outline drawing for actual layout

nSPx	nSPy
2	2

DIMENSIONS in mm

P	Ax	Ay	Bx	By	C	D	SLx	SLy	SPx tot	SPy tot	SPx	SPy	Gx	Gy	Hx	Hy
0.500	6.000	6.000	4.200	4.200	0.900	0.290	3.100	3.100	1.800	1.800	0.700	0.700	5.300	5.300	6.250	6.250

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